

ABSTRACT OF THE DISCLOSURE

Provided are a hybrid integrated circuit device in which fine patterns can be formed while current-carrying capacitances are ensured, and a method of manufacturing the same. The hybrid integrated circuit device of the present invention includes conductive patterns formed on a front surface of a circuit substrate and circuit elements electrically connected respectively to the conductive patterns. The conductive patterns include a first conductive pattern and a second conductive pattern formed more thickly than the first conductive pattern. The second conductive pattern includes a protruding portion protruding in a thickness direction thereof.